belkin

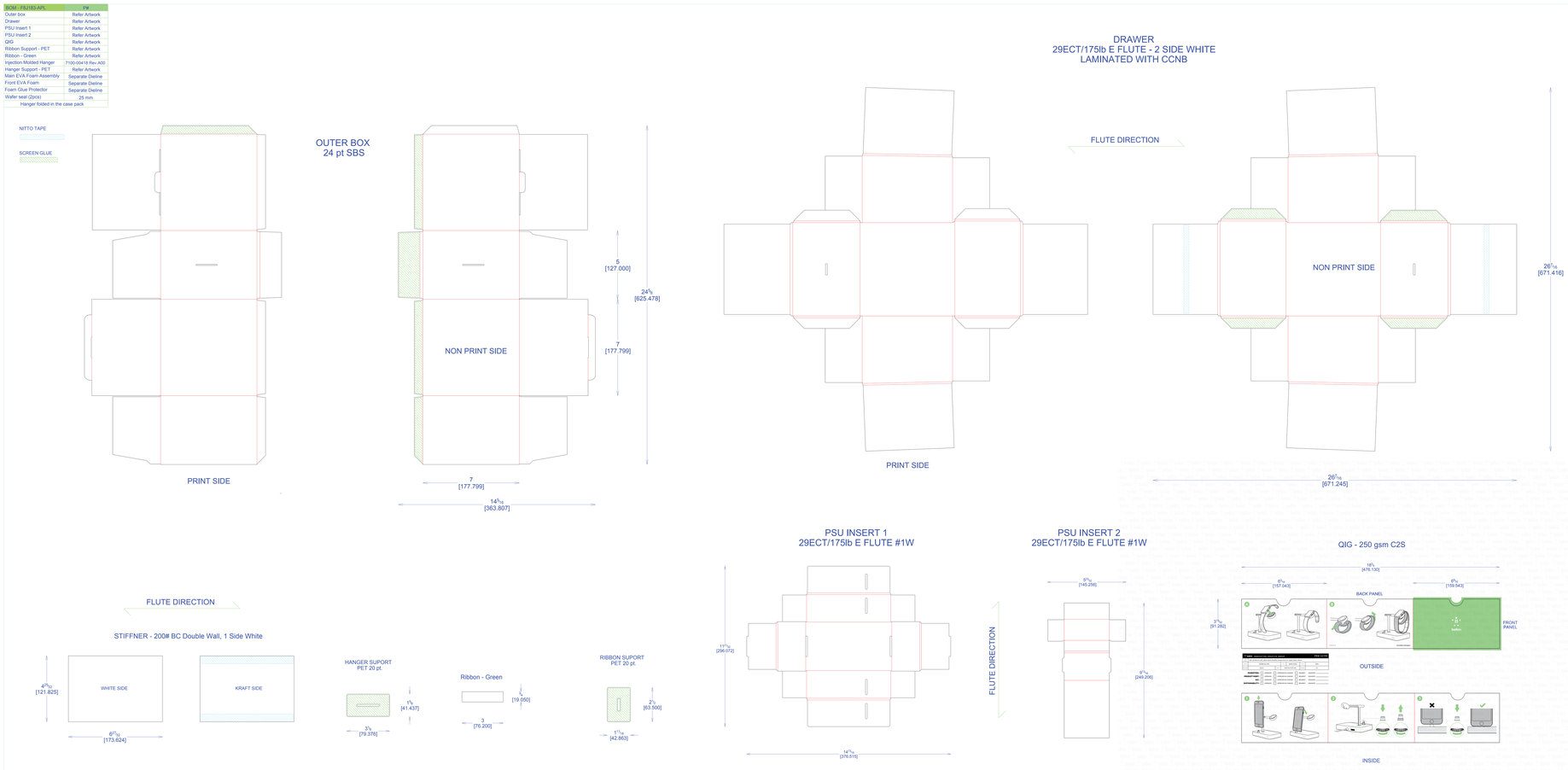
Die Line File: IDL_F8J183-APL_PROJECT LEAPFROG_PACKAGE

Artwork File:

REV
I 00

DIE LAYOUT

BOM - F8J183-APL	PN
Outer box	Refer Artwork
Drawer	Refer Artwork
PSU Insert 1	Refer Artwork
PSU Insert 2	Refer Artwork
QIG	Refer Artwork
Ribbon Support - PET	Refer Artwork
Ribbon - Green	Refer Artwork
Injection Molded Hanger	7100-00418 Rev A00
Hanger Support - PET	Refer Artwork
Main EVA Foam Assembly	Separate Dieline
Front EVA Foam	Separate Dieline
Foam Glue Protector	Separate Dieline
Wafer seal (2pcs)	25 mm
Hanger folded in the case pack	



Business Unit: Core

Program Manager:

Packaging Engineer: Ramji Jayaram

Retail Outside Dimension (Including Hang Tab)

L x W x D (in): 0 x 0 x 0

L x W x D (mm): 0.00 x 0.00 x 0.00

DIE/MATERIAL SPECS:

Material: Please refer to drawing

Blank Size (in): 105.235 x 47.607

Blank Size (mm): 2672.970 x 1209.213

This dieline works for following skus (if any):

Universal

Unit: IN/MM

Side Shown: PRINT SIDE

Flute/Grain: vertical

Tolerance:+/- 1/32" - 0.8mm

Drawing Scale 1:1

RELEASE DATE: 05/12/2016

DIELINE:

Intermediate

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PRINT SPECS:

Color Plates:

Finish:

Notes:

DO NOT PRINT
DIE LINES, PRINTERS NOTES